This document can handle board shapes up to 7.5in x 10in, although our panel vendors top out at 7in x 10in. To resize the board shape, do the following:

Select lines on all board outlines and delete them in single layer mode...

Select lines on all board outlines and delete them in single layer mode...

Draw a rectangle using lines (example will be for a 4 x 6 board)

Enter Place Line mode (keyboard Alt)

Keyboard 'J' to jump to origin, hit enter

Keyboard 'J' to jump to location, set x to 6000, hit enter twice

Keyboard 'J' to jump to location, set y to 0 and y to 1000, hit enter twice

Keyboard 'J' to jump to origin, hit enter

Hit ESC twice to exit place line mode.

Select lines on all board outlines

Menu Design > Board Outline from Selected Objects (keyboard del)

To define a Keep-Out that mirrors the board outline:

Menu Design > Board Outline from Board Shape (keyboard del)

Set the Keep-Out Layer as the layer, set width as preferred

Ensure Route Tool Outline is selected, hit enter

If you resize the board, don’t forget to move the drill table strings on the Drill Drawing Layer...they should be just to the right of your board shape.
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